



Material Content Data Sheet



Sales Product Name		BSS215P H6327		Issued		29. August 2013		
MA#		MA000939874						
Package		PG-SOT23-3-5		Weight*		9.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		470	
	noble metal	gold	7440-57-5	0.017	0.18		1824	
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20669	22963
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		964	
	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		321	
	non noble metal	copper	7440-50-8	3.000	31.99	32.13	319905	321254
wire	non noble metal	copper	7440-50-8	0.039	0.41	0.41	4130	4130
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6054	
	plastics	epoxy resin	-	1.221	13.02		130155	
	inorganic material	silicondioxide	60676-86-0	4.400	46.90	60.53	469164	605373
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15955	15955
plating	noble metal	silver	7440-22-4	0.284	3.03	3.03	30325	30325
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com